A Multi-Drop Transmission-Line Interconnect in Si LSI

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1. Background and purpose

Global Interconnect

Delay & Power consumption: The enduring obstacles

Transmission Line Interconnect

- Signals can propagate at near speed-of-light.
- The conventional on-chip TL interconnects are peer-to-peer ones.

We propose the on-chip TL interconnect with branches.

2. Branching structure



3. Test circuit for branches

Transistors at branching nodes are modeled as capacitors.

- •0.18µm CMOS process
- •Line width: $2.4 \mu m$



 Assumption ; Acceptable degradation of eye-height is 5%.

→75fF can be connected to the singleended transmission line.



4. Measurement results



- We have proposed an on-chip transmission-line interconnect with branches.
- In the measurement result, the proposed interconnect realizes 4Gbps signal transmission.
- Transmission line interconnects can improve delay and power of a branching globalinterconnect as well as a peer-to-peer interconnect, which will contribute speeding-up and power saving of LSI.